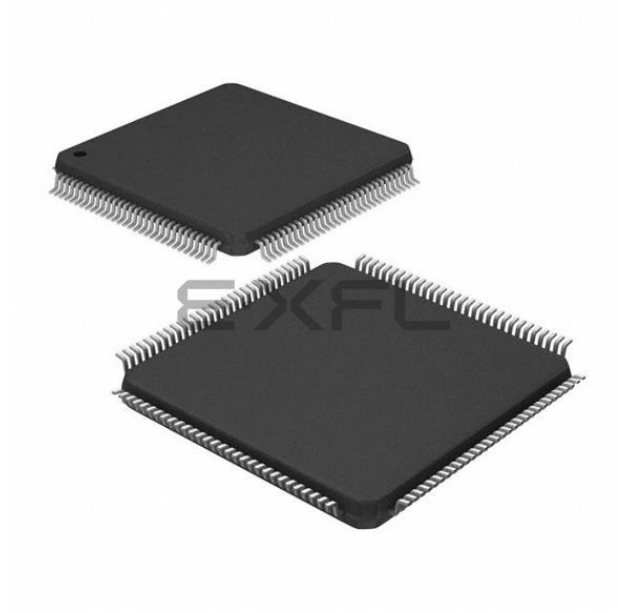
Infineon Technologies - MB90922NCSPMC-GS-245E1 Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	F²MC-16LX
Core Size	16-Bit
Speed	32MHz
Connectivity	CANbus, LINbus, UART/USART
Peripherals	LCD, LVD, POR, PWM, WDT
Number of I/O	93
Program Memory Size	256KB (256K x 8)
Program Memory Type	Mask ROM
EEPROM Size	-
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 8x8/10b
Oscillator Type	External
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	120-LQFP
Supplier Device Package	120-LQFP (16x16)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb90922ncspmc-gs-245e1

FUJITSU SEMICONDUCTOR
DATA SHEET

DS07-13750-4E

16-bit Microcontroller

CMOS

F²MC-16LX MB90920 Series

MB90F922NC/F922NCS/922NCS/F923NC/F923NCS/ MB90F924NC/F924NCS/V920-101/V920-102

■ DESCRIPTION

The MB90920 series is a family of general-purpose FUJITSU SEMICONDUCTOR 16-bit microcontrollers designed for applications such as vehicle instrument panel control.

The instruction set retains the AT architecture from the F²MC-8L and F²MC-16LX families, with further refinements including high-level language instructions, extended addressing modes, improved multiplication and division operations (signed), and bit processing. In addition, long word processing is made possible by the inclusion of a built-in 32-bit accumulator.

Note : F²MC is the abbreviation of FUJITSU Flexible Microcontroller.

■ FEATURES

- Clock
  Built-in PLL clock frequency multiplication circuit.
  Selection of machine clocks (PLL clocks) is allowed among frequency division by two on oscillation clock, and multiplication of 1 to 8 times of oscillation clock (for 4 MHz oscillation clock, 4 MHz to 32 MHz).
  Operation by sub clock (up to 50 kHz : 100 kHz oscillation clock divided by two) is allowed.
- 16-bit input capture (8 channels)
  Detects rising, falling, or both edges.
  16-bit capture register × 8
  The value of a 16-bit free-run timer counter is latched upon detection of an edge input to pin and an interrupt request is generated.

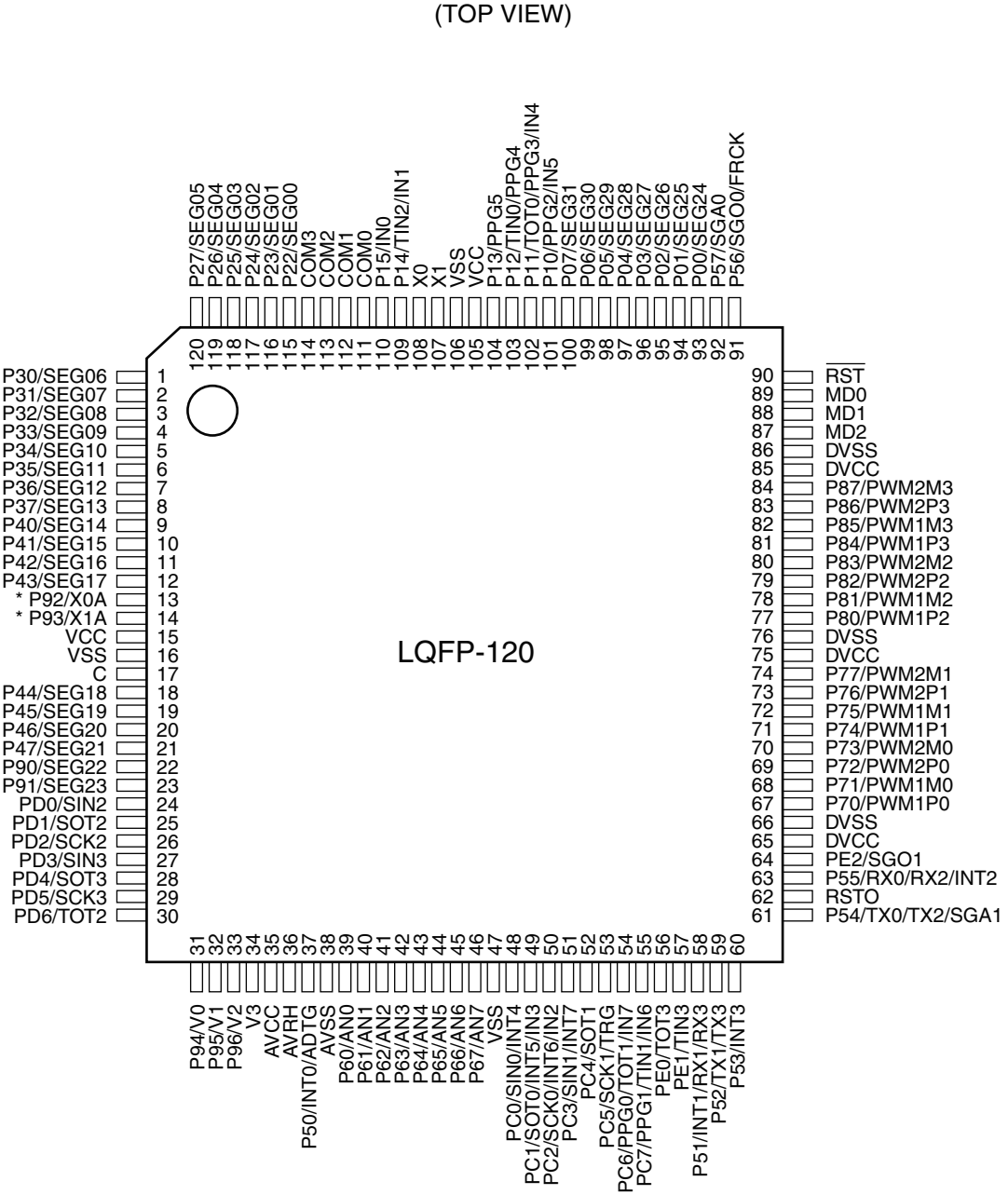
(Continued)

For the information for microcontroller supports, see the following web site.
This web site includes the **"Customer Design Review Supplement"** which provides the latest cautions on system development and the minimal requirements to be checked to prevent problems before the system development.

http://edevice.fujitsu.com/micom/en-support/

2010.9

■ PIN ASSIGNMENT



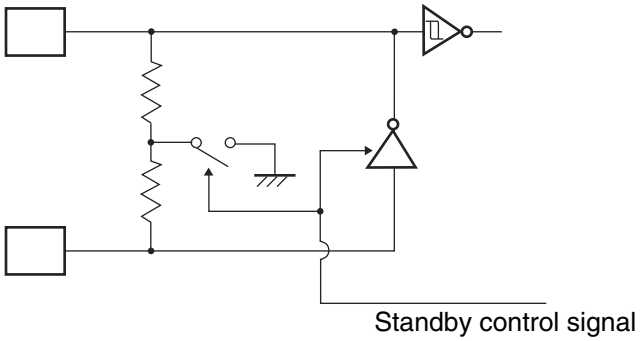
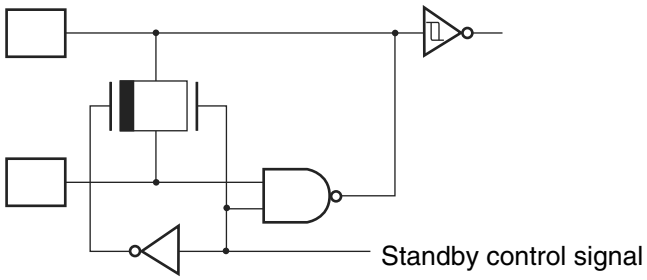
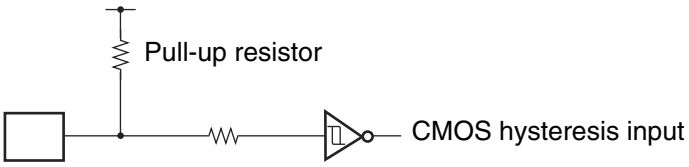
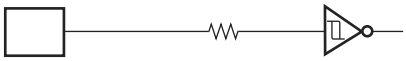
(FPT-120P-M21)

* : MB90V920-101, MB90F922NCS,MB90F923NCS,MB90F924NCS,MB90922NCS : P92, P93
MB90V920-102, MB90F922NC,MB90F923NC,MB90F924NC : X0A, X1A

Pin no.	Pin name	I/O circuit type*1	Function
33	P96	G	General-purpose I/O port
	V2		LCD controller/driver reference power supply pin
34	V3	—	LCD controller/driver reference power supply pin
48	PC0	J	General-purpose I/O port
	SIN0		UART ch.0 serial data input pin
	INT4		INT4 external interrupt input pin
49	PC1	I	General-purpose I/O port
	SOT0		UART ch.0 serial data output pin
	INT5		INT5 external interrupt input pin
	IN3		Input capture ch.3 trigger input pin
50	PC2	I	General-purpose I/O port
	SCK0		UART ch.0 serial clock I/O pin
	INT6		INT6 external interrupt input pin
	IN2		Input capture ch.2 trigger input pin
51	PC3	J	General-purpose I/O port
	SIN1		UART ch.1 serial data input pin
	INT7		INT7 external interrupt input pin
52	PC4	I	General-purpose I/O port
	SOT1		UART ch.1 serial data output pin
53	PC5	I	General-purpose I/O port
	SCK1		UART ch.1 serial clock I/O pin
	TRG		16-bit PPG ch.0 to ch.5 external trigger input pin
54	PC6	I	General-purpose I/O port
	PPG0		16-bit PPG ch.0 output pin
	TOT1		16-bit reload timer ch.1 TOT output pin
	IN7		Input capture ch.7 trigger input pin
55	PC7	I	General-purpose I/O port
	PPG1		16-bit PPG ch.1 output pin
	TIN1		16-bit reload timer ch.1 TIN input pin
	IN6		Input capture ch.6 trigger input pin
24	PD0	J	General-purpose I/O port
	SIN2		UART ch.2 serial data input pin
25	PD1	I	General-purpose I/O port
	SOT2		UART ch.2 serial data output pin

(Continued)

■ I/O CIRCUIT TYPE

Type	Circuit	Remarks
A		Oscillation circuit High-speed oscillation feedback resistance : approx. 1 MΩ (Flash memory product/MASK ROM product/Evaluation product)
B		Oscillation circuit Low-speed oscillation feedback resistance : approx. 10 MΩ
C		Input-only pin (with pull-up resistance) • Attached pull-up resistor : approx. 50 kΩ • CMOS hysteresis input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.2 V_{CC})
D		Input-only pin • CMOS hysteresis input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.2 V_{CC}) Note: The MD2 pin of the Flash memory products uses this circuit type.

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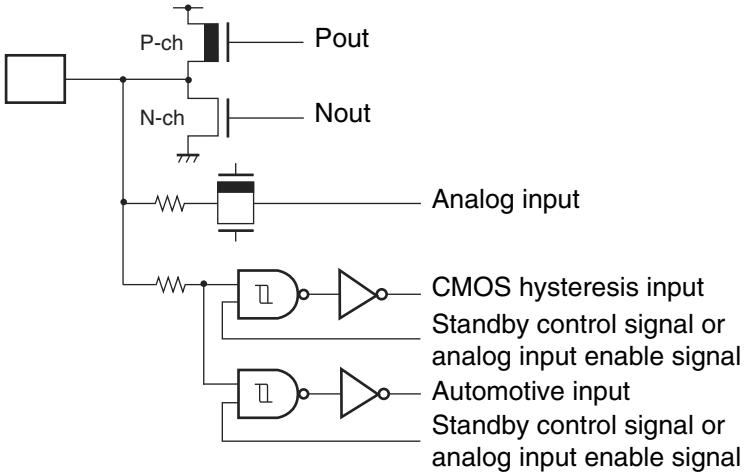
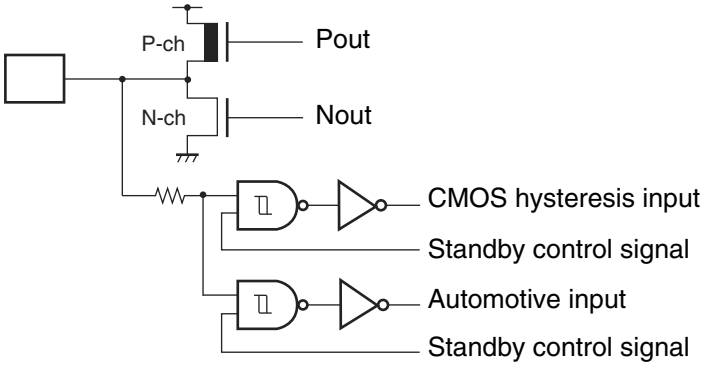
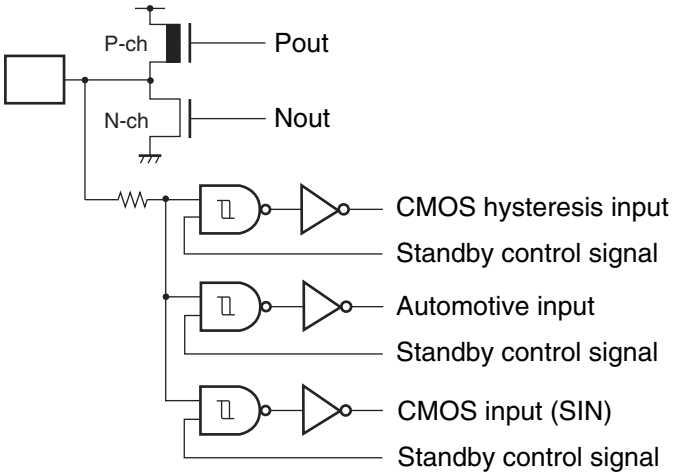
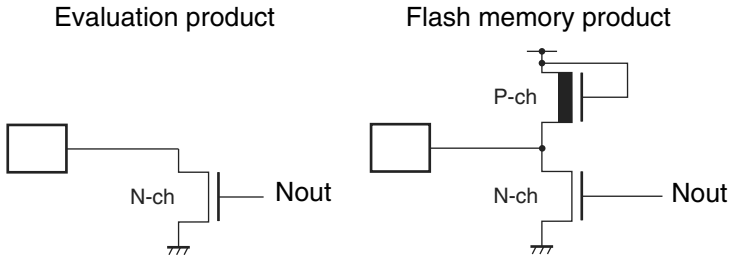
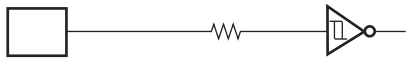
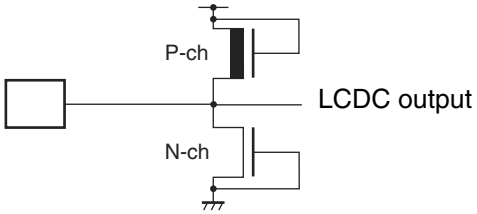
Type	Circuit	Remarks
H		A/D converter input common general-purpose port • CMOS output (I_{OH}/I_{OL} = ± 4 mA) • CMOS hysteresis input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.2 V_{CC}) • Automotive input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.5 V_{CC})
I		General-purpose port • CMOS output (I_{OH}/I_{OL} = ± 4 mA) • CMOS hysteresis input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.2 V_{CC}) • Automotive input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.5 V_{CC})
J		General-purpose port (serial input) • CMOS output (I_{OH}/I_{OL} = ± 4 mA) • CMOS hysteresis input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.2 V_{CC}) • CMOS input (SIN) (V_{IH}/V_{IL} = 0.7 V_{CC}/0.3 V_{CC}) • Automotive input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.5 V_{CC})

(Continued)

(Continued)

Type	Circuit	Remarks
N		N-ch open-drain pin I_{OL} = 4 mA
O		Input-only pin Automotive input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.5 V_{CC})
P		LCDC output pin (COM pin)

■ HANDLING DEVICES

• Strictly observe maximum rated voltages (preventing latch-up)

In CMOS IC devices, a condition known as latch-up may occur if voltages higher than V_{CC} or lower than V_{SS} are applied to input or output pins other than medium or high withstand voltage pins, or if the voltage applied between VCC and VSS pins exceeds the rated voltage level. If a latch-up occurs, the power supply current may increase dramatically and may destroy semiconductor elements. When using semiconductor devices, always take sufficient care to avoid exceeding maximum ratings.

When the analog system power supply is switched on or off, be careful not to apply the analog power supply (AV_{CC}, AVRH), the analog input voltages and the power supply voltage for the high current output buffer pins (DV_{CC}) in excess of the digital power supply voltage (V_{CC}).

Once the digital power supply voltage (V_{CC}) has been disconnected, the analog power supply (AV_{CC}, AVRH) and the power supply voltage for the high current output buffer pins (DV_{CC}) may be turned on in any sequence.

• Supply voltage stabilization

Rapid fluctuations in the power supply voltage can cause malfunctions even if the Vcc power supply voltage remains within the warranted operating range. It is recommended that the power supply be stabilized such that ripple fluctuations (P-P value) at commercial frequencies (50 Hz/60 Hz) be limited to within 10% of the standard V_{CC} value, and that transient fluctuations due to power supply switching, etc. be limited to a rate of 0.1 V/ms or less.

• Precautions when turning the power on

In order to prevent the built-in step-down circuits from malfunctioning, the time taken for the voltage to rise (0.2 V to 2.7 V) during power-on should be less than 50 μs.

• Handling unused pins

If unused input pins are left open, they may cause malfunctions or latch-up which may lead to permanent damage to the semiconductor. Unused input pins should therefore be pulled up or pulled down through a resistor of at least 2 kΩ.

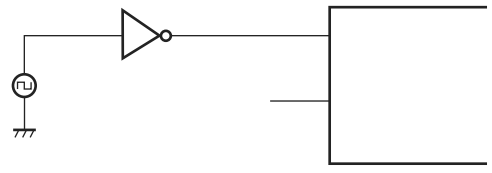
Unused input/output pins may be set to the output state and left open, or set to the input state and connected to a pull-up or pull-down resistance of 2 kΩ or more.

• Handling A/D converter power supply pins

Even if the A/D converter is not used, the power supply pins should be connected such as $AV_{CC} = V_{CC}$, and $AV_{SS} = AVRH = V_{SS}$.

• Notes on using an external clock

Even when an external clock is used, an oscillation stabilization wait time is required following power-on reset or release from sub clock mode or stop mode. Furthermore, only the X0A pin should be driven when an external clock is used, with the X1A pin open as shown in the following diagram. Do not use high-speed oscillation pins (X0 and X1) for external clock input.



Sample external clock connection

• **Notes on operating in PLL clock mode**

On this microcontroller, if in case the crystal oscillator breaks off or an external reference clock input stops while the PLL clock mode is selected, a self-oscillator circuit contained in the PLL may continue its operation at its self-running frequency. However, FUJITSU SEMICONDUCTOR will not guarantee results of operations if such failure occurs.

• **Crystal oscillator circuit**

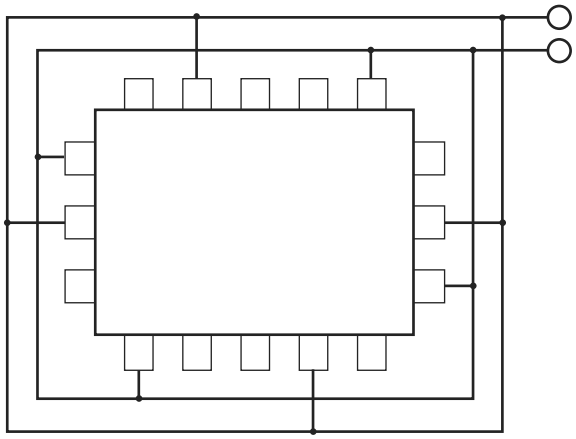
Noise around the X0/X1, or X0A/X1A pins may cause this device to operate abnormally. In the interest of stable operation it is strongly recommended that printed circuit artwork places ground bypass capacitors as close as possible to the X0/X1, X0A/X1A and crystal oscillator (or ceramic oscillator) and that oscillator lines do not cross the lines of other circuits.

Please ask each crystal maker to evaluate the oscillational characteristics of the crystal and this device.

• **Power supply pins**

Devices including multiple VCC or VSS pins are designed such that pins that need to be at the same potential are interconnected internally to prevent malfunctions such as latch-up. To reduce unnecessary radiation, prevent malfunctioning of the strobe signal due to the rise of ground level, and observe the standard for total output current, be sure to connect the VCC and VSS pins to the power supply and ground externally.

Always connect all of the VCC pins to the same potential and all of the VSS pins to ground as shown in the following diagram. The device will not operate correctly if multiple VCC or VSS pins are connected to different voltages, even if those voltages are within the guaranteed operating ranges.



Power supply input pins (Vcc/Vss)

In addition, care must be given to connecting the VCC and VSS pins of this device to the current supply source with as low impedance as possible. It is recommended that a 1.0 μF bypass capacitor be connected between the VCC and VSS pins as close to the pins as possible.

• **Sequence for connecting the A/D converter power supply and analog inputs**

The A/D converter power supply (AV_{CC}, AVRH) and analog inputs (AN0 to AN7) must be applied after the digital power supply (V_{CC}) is switched on. When turning the power off, the A/D converter power supply and analog inputs must be disconnected before the digital power supply is switched off (V_{CC}). Ensure that AVRH does not exceed AVcc during either power-on or power-off. Even when pins which double as analog input pins are used as input ports, be sure that the input voltage does not exceed AV_{CC} (turning on/off the analog and digital power supplies simultaneously is acceptable).

- **Handling the power supply for high-current output buffer pins** (DV_{CC}, DV_{SS})

  - **Flash memory products and MASK ROM products (MB90F922NC/F922NCS/922NCS/F923NC/ F923NCS/F924NC/F924NCS)**

    In the Flash memory products and MASK ROM products, the power supply for the high-current output buffer pins (DV_{CC}, DV_{SS}) is isolated from the digital power supply (V_{CC}).
    Therefore, DVcc can therefore be set to a higher voltage than Vcc. If the power supply for the high-current output buffer pins (DV_{CC}, DV_{SS}) is supplied before the digital power supply (V_{CC}), however, care needs to be taken because it is possible that the port 7 or port 8 stepping motor outputs may momentarily output an “H” or “L” level. In order to prevent this, connect the digital power supply (V_{CC}) prior to connecting the power supply for the high-current output buffer pins. Even when the high-current output buffer pins are used as general-purpose ports, power should be supplied to the power supply pins for the high-current output buffer pins (DV_{CC}, DV_{SS}).

  - **Evaluation product** (**MB90V920-101**/**MB90V920-102**)

    In the evaluation products, the power supply for the high-current output buffer pins (DV_{CC}, DV_{SS}) is not isolated from the digital power supply (V_{CC}). Therefore, DV_{CC} must therefore be set to a lower voltage than Vcc. The power supply for the high-current output buffer pins (DV_{CC}, DV_{SS}) must always be applied after the digital power supply (V_{CC}) has been connected, and disconnected before the digital power supply (Vcc) is disconnected (the power supply for the high-current output buffer pins may also be connected and disconnected simultaneously with the digital power supply).
    Even when the high-current output buffer pins are used as general-purpose ports, power should be supplied to the power supply pins for the high-current output buffer pins (DV_{CC}, DV_{SS}).

- **Pull-up/pull-down resistors**

MB90920 series does not support internal pull-up/pull-down resistors. Use external components as necessary.

- **Precautions when not using a sub clock signal**

If the X0A and X1A pins are not connected to an oscillator, apply a pull-down resistance to the X0A pin and leave the X1A pin open.

- **Notes on operating when the external clock is stopped**

The MB90920 series is not guaranteed to operate correctly using the internal oscillator circuit when there is no external oscillator or the external clock input is stopped.

- **Flash memory security function**

A security bit is located within the Flash memory region. The security function is activated by writing the protection code 01_H to the security bit.
Do not write the value 01_H to this address if you are not using the security function.
Please refer to following table for the address of the security bit.

	Flash memory size	Address for security bit
MB90F922NC MB90F922NCS	Built-in 2 Mbits Flash Memory	$FC0001_H$
MB90F923NCS	Built-in 3 Mbits Flash Memory	$F80001_H$
MB90F924NCS	Built-in 4 Mbits Flash Memory	$F80001_H$

Address	Register name	Symbol	Read/write	Resource name	Initial value
0000D4H	Lower timer control status register 2	TMCSR2L	R/W	16-bit reload timer 2	00000000B
0000D5H	Higher timer control status register 2	TMCSR2H	R/W		XXX10000B
0000D6H	Lower timer control status register 3	TMCSR3L	R/W	16-bit reload timer 3	00000000B
0000D7H	Higher timer control status register 3	TMCSR3H	R/W		XXX10000B
0000D8H	Lower sound control register 1	SGCRL1	R/W	Sound generator 1	00000000B
0000D9H	Higher sound control register 1	SGCRH1	R/W		0XXXX100B
0000DAH	Lower PPG3 control status register	PCNTL3	R/W	16-bit PPG3	00000000B
0000DBH	Higher PPG3 control status register	PCNTH3	R/W		00000001B
0000DCH	Lower PPG4 control status register	PCNTL4	R/W	16-bit PPG4	00000000B
0000DDH	Higher PPG4 control status register	PCNTH4	R/W		00000001B
0000DEH	Lower PPG5 control status register	PCNTL5	R/W	16-bit PPG5	00000000B
0000DFH	Higher PPG5 control status register	PCNTH5	R/W		00000001B
0000E0H	Serial mode register 2	SMR2	R/W, W	UART (LIN/SCI) 2	00000000B
0000E1H	Serial control register 2	SCR2	R/W, W		00000000B
0000E2H	Reception/transmission data register 2	RDR2/ TDR2	R/W		00000000B
0000E3H	Serial status register 2	SSR2	R/W, R		00001000B
0000E4H	Extended communication control register 2	ECCR2	R/W, R		000000XXB
0000E5H	Extended status control register 2	ESCR2	R/W		00000100B
0000E6H	Baud rate generator register 20	BGR20	R/W		00000000B
0000E7H	Baud rate generator register 21	BGR21	R/W, R		00000000B
0000E8H	Serial mode register 3	SMR3	R/W, W	UART (LIN/SCI) 3	00000000B
0000E9H	Serial control register 3	SCR3	R/W, W		00000000B
0000EAH	Reception/transmission data register 3	RDR3/ TDR3	R/W		00000000B
0000EBH	Serial status register 3	SSR3	R/W, R		00001000B
0000ECH	Extended communication control register 3	ECCR3	R/W, R		000000XXB
0000EDH	Extended status control register 3	ESCR3	R/W		00000100B
0000EEH	Baud rate generator register 30	BGR30	R/W		00000000B
0000EFH	Baud rate generator register 31	BGR31	R/W, R		00000000B
001FF0H	Program address detection register 0	PADR0	R/W	Address match detection	XXXXXXXXB
001FF1H	Program address detection register 1	PADR0	R/W		XXXXXXXXB
001FF2H	Program address detection register 2	PADR0	R/W		XXXXXXXXB
001FF3H	Program address detection register 3	PADR1	R/W		XXXXXXXXB
001FF4H	Program address detection register 4	PADR1	R/W		XXXXXXXXB
001FF5H	Program address detection register 5	PADR1	R/W		XXXXXXXXB

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Address				Register	Abbre-viation	Access	Initial Value
CAN0	CAN1	CAN2	CAN3				
003A40H	003B40H	003740H	003840H	ID register 8	IDR8	R/W	XXXXXXXXB XXXXXXXXB
003A41H	003B41H	003741H	003841H				
003A42H	003B42H	003742H	003842H				XXXXX---B XXXXXXXXB
003A43H	003B43H	003743H	003843H				
003A44H	003B44H	003744H	003844H	ID register 9	IDR9	R/W	XXXXXXXXB XXXXXXXXB
003A45H	003B45H	003745H	003845H				
003A46H	003B46H	003746H	003846H				XXXXX---B XXXXXXXXB
003A47H	003B47H	003747H	003847H				
003A48H	003B48H	003748H	003848H	ID register 10	IDR10	R/W	XXXXXXXXB XXXXXXXXB
003A49H	003B49H	003749H	003849H				
003A4AH	003B4AH	00374AH	00384AH				XXXXX---B XXXXXXXXB
003A4BH	003B4BH	00374BH	00384BH				
003A4CH	003B4CH	00374CH	00384CH	ID register 11	IDR11	R/W	XXXXXXXXB XXXXXXXXB
003A4DH	003B4DH	00374DH	00384DH				
003A4EH	003B4EH	00374EH	00384EH				XXXXX---B XXXXXXXXB
003A4FH	003B4FH	00374FH	00384FH				
003A50H	003B50H	003750H	003850H	ID register 12	IDR12	R/W	XXXXXXXXB XXXXXXXXB
003A51H	003B51H	003751H	003851H				
003A52H	003B52H	003752H	003852H				XXXXX---B XXXXXXXXB
003A53H	003B53H	003753H	003853H				
003A54H	003B54H	003754H	003854H	ID register 13	IDR13	R/W	XXXXXXXXB XXXXXXXXB
003A55H	003B55H	003755H	003855H				
003A56H	003B56H	003756H	003856H				XXXXX---B XXXXXXXXB
003A57H	003B57H	003757H	003857H				
003A58H	003B58H	003758H	003858H	ID register 14	IDR14	R/W	XXXXXXXXB XXXXXXXXB
003A59H	003B59H	003759H	003859H				
003A5AH	003B5AH	00375AH	00385AH				XXXXX---B XXXXXXXXB
003A5BH	003B5BH	00375BH	00385BH				
003A5CH	003B5CH	00375CH	00385CH	ID register 15	IDR15	R/W	XXXXXXXXB XXXXXXXXB
003A5DH	003B5DH	00375DH	00385DH				
003A5EH	003B5EH	00375EH	00385EH				XXXXX---B XXXXXXXXB
003A5FH	003B5FH	00375FH	00385FH				

List of Message Buffers (Data register)

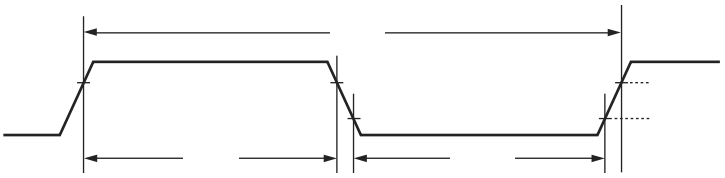
Address				Register	Abbre-viation	Access	Initial Value
CAN0	CAN1	CAN2	CAN3				
003A80H to 003A87H	003B80H to 003B87H	003780H to 003787H	003880H to 003887H	Data register 0 (8 bytes)	DTR0	R/W	XXXXXXXXB to XXXXXXXXB
003A88H to 003A8FH	003B88H to 003B8FH	003788H to 00378FH	003888H to 00388FH	Data register 1 (8 bytes)	DTR1	R/W	XXXXXXXXB to XXXXXXXXB
003A90H to 003A97H	003B90H to 003B97H	003790H to 003797H	003890H to 003897H	Data register 2 (8 bytes)	DTR2	R/W	XXXXXXXXB to XXXXXXXXB
003A98H to 003A9FH	003B98H to 003B9FH	003798H to 00379FH	003898H to 00389FH	Data register 3 (8 bytes)	DTR3	R/W	XXXXXXXXB to XXXXXXXXB
003AA0H to 003AA7H	003BA0H to 003BA7H	0037A0H to 0037A7H	0038A0H to 0038A7H	Data register 4 (8 bytes)	DTR4	R/W	XXXXXXXXB to XXXXXXXXB
003AA8H to 003AAFH	003BA8H to 003BAFH	0037A8H to 0037AFH	0038A8H to 0038AFH	Data register 5 (8 bytes)	DTR5	R/W	XXXXXXXXB to XXXXXXXXB
003AB0H to 003AB7H	003BB0H to 003BB7H	0037B0H to 0037B7H	0038B0H to 0038B7H	Data register 6 (8 bytes)	DTR6	R/W	XXXXXXXXB to XXXXXXXXB
003AB8H to 003ABFH	003BB8H to 003BBFH	0037B8H to 0037BFH	0038B8H to 0038BFH	Data register 7 (8 bytes)	DTR7	R/W	XXXXXXXXB to XXXXXXXXB
003AC0H to 003AC7H	003BC0H to 003BC7H	0037C0H to 0037C7H	0038C0H to 0038C7H	Data register 8 (8 bytes)	DTR8	R/W	XXXXXXXXB to XXXXXXXXB
003AC8H to 003ACFH	003BC8H to 003BCFH	0037C8H to 0037CFH	0038C8H to 0038CFH	Data register 9 (8 bytes)	DTR9	R/W	XXXXXXXXB to XXXXXXXXB
003AD0H to 003AD7H	003BD0H to 003BD7H	0037D0H to 0037D7H	0038D0H to 0038D7H	Data register 10 (8 bytes)	DTR10	R/W	XXXXXXXXB to XXXXXXXXB
003AD8H to 003ADFH	003BD8H to 003BDFH	0037D8H to 0037DFH	0038D8H to 0038DFH	Data register 11 (8 bytes)	DTR11	R/W	XXXXXXXXB to XXXXXXXXB
003AE0H to 003AE7H	003BE0H to 003BE7H	0037E0H to 0037E7H	0038E0H to 0038E7H	Data register 12 (8 bytes)	DTR12	R/W	XXXXXXXXB to XXXXXXXXB
003AE8H to 003AEFH	003BE8H to 003BEFH	0037E8H to 0037EFH	0038E8H to 0038EFH	Data register 13 (8 bytes)	DTR13	R/W	XXXXXXXXB to XXXXXXXXB
003AF0H to 003AF7H	003BF0H to 003BF7H	0037F0H to 0037F7H	0038F0H to 0038F7H	Data register 14 (8 bytes)	DTR14	R/W	XXXXXXXXB to XXXXXXXXB
003AF8H to 003AFFH	003BF8H to 003BFFH	0037F8H to 0037FFH	0038F8H to 0038FFH	Data register 15 (8 bytes)	DTR15	R/W	XXXXXXXXB to XXXXXXXXB

(V_{CC} = 5.0 V ±10%, V_{SS} = DV_{SS} = AV_{SS} = 0.0 V, T_A = − 40 °C to +105 °C)

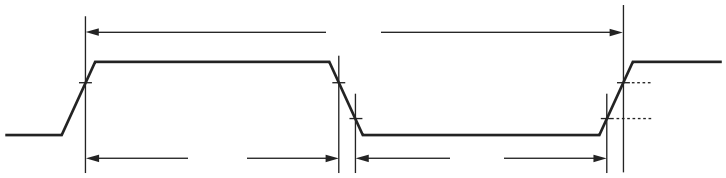
Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Input leakage current	I_{IL}	All input pins	V_{CC} = DV_{CC} = AV_{CC} = 5.5 V, V_{SS} < V_I < V_{CC}	—	—	10	µA	
Input capacitance 1	C_{IN1}	All pins except VCC, VSS, DVCC, DVSS, AVCC, AVSS, C, P70 to P77, P80 to P87	—	—	—	15	pF	
Input capacitance 2	C_{IN2}	P70 to P77, P80 to P87	—	—	—	45	pF	
Pull-up resistance	R_{UP}	$\overline{RST}$	—	25	50	100	kΩ	
Pull-down resistance	R_{DOWN}	MD2	—	—	—	100	kΩ	Excluding Flash memory product
General-purpose output “H” voltage	V_{OH1}	All pins except P70 to P77, P80 to P87	V_{CC} = 4.5 V, I_{OH} = –4.0 mA	V_{CC} – 0.5	—	—	V	
Stepping motor output “H” voltage	V_{OH2}	P70 to P77, P80 to P87	V_{CC} = 4.5 V, I_{OH} = –30.0 mA	V_{CC} – 0.5	—	—	V	
General-purpose output “L” voltage	V_{OL1}	All pins except P70 to P77, P80 to P87	V_{CC} = 4.5 V, I_{OL} = 4.0 mA	—	—	0.4	V	
Stepping motor output “L” voltage	V_{OL2}	P70 to P77, P80 to P87	V_{CC} = 4.5 V, I_{OL} = 30.0 mA	—	—	0.55	V	
Stepping motor output phase variation “H”	ΔV_{OH}	PWM1Pn, PWM1Mn, PWM2Pn, PWM2Mn, n = 0 to 3	V_{CC} = 4.5 V, I_{OH} = –30.0 mA, maximum deviation V_{OH2}	—	—	90	mV	
Stepping motor output phase variation “L”	ΔV_{OL}	PWM1Pn, PWM1Mn, PWM2Pn, PWM2Mn, n = 0 to 3	V_{CC} = 4.5 V, I_{OL} = 30.0 mA, maximum deviation V_{OH2}	—	—	90	mV	
LCD internal divider resistance	R_{LCD}	Between V0 and V1, Between V1 and V2, Between V2 and V3	—	50	100	200	kΩ	Evaluation product
				8.75	12.5	17.0	kΩ	Flash memory product

(Continued)

• X0, X1 clock timing



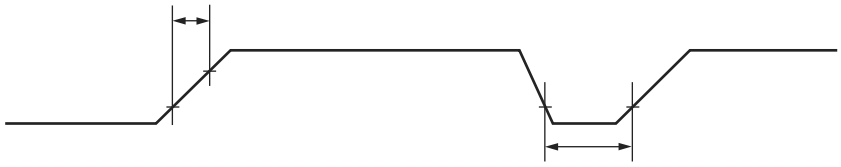
• X0A, X1A clock timing



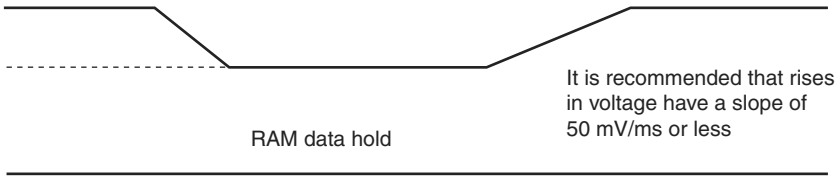
(3) Power-on reset

(V_{CC} = 2.7 V to 3.6 V, V_{SS} = 0.0 V, T_A = − 40 °C to +105 °C)

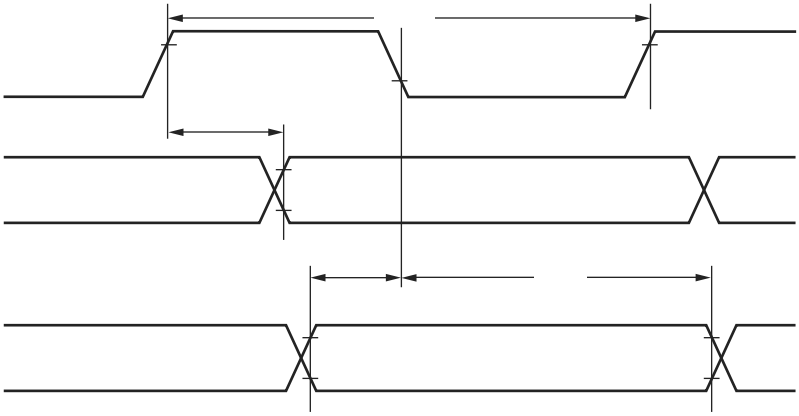
Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Power supply rise time	t_R	VCC	—	0.05	30	ms	
Power off time	t_{OFF}			1	—	ms	Waiting time until power-on



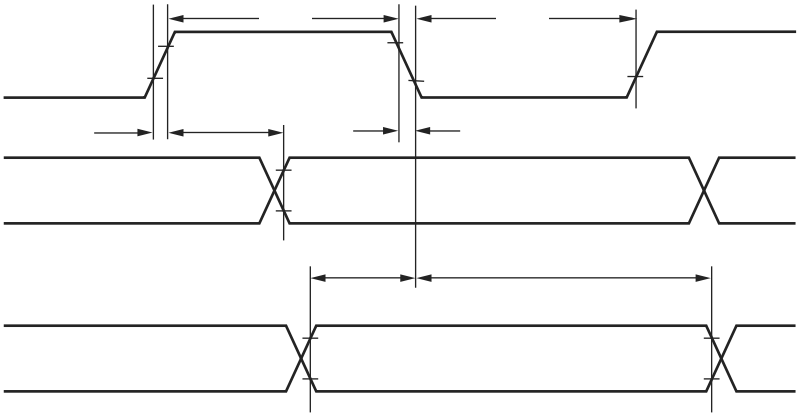
Note : Extreme variations in power supply voltage may trigger a power-on reset. When the power supply voltage is changed during operation, it is recommended that increases in the voltage smoothed out as shown in the following diagram. The PLL clock of the device should not be in use when varying the voltage. However, the PLL clock may continue to be used if the rate of the voltage drop is 1 V/s or less.



- Internal shift clock mode



- External shift clock mode



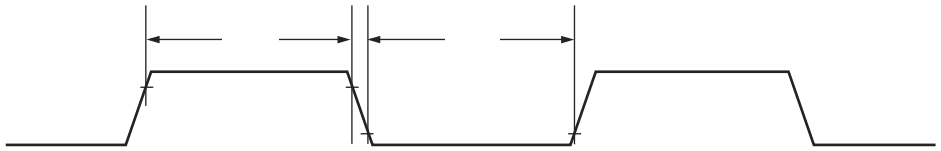
(6) Trigger input timing

(V_{CC} = 5.0 V±10%, V_{SS} = AV_{SS} = 0.0 V, T_A = –40 °C to +105 °C)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{TRGH}, t_{TRGL}	INT0 to INT7	—	200	—	ns	During normal operation
		ADTG	—	t_{CP} + 200	—	ns	

Note : t_{CP} is the internal operating clock cycle time. Refer to “ (1) Clock timing”.

- Trigger input timing



5. A/D Converter

(1) Electrical Characteristics

(V_{CC} = AV_{CC} = AVRH = 4.0 V to 5.5 V, V_{SS} = AV_{SS} = 0.0 V, T_A = –40 °C to +105 °C)

Parameter	Symbol	Pin name	Value			Unit	Remarks
			Min	Typ	Max		
Resolution	—	—	—	—	10	bit	
Total error	—	—	– 3.0	—	+ 3.0	LSB	
Non-linear error	—	—	– 2.5	—	+ 2.5	LSB	
Differential linear error	—	—	– 1.9	—	+ 1.9	LSB	
Zero transition voltage	V_{OT}	AN0 to AN7	AV_{SS} – 1.5 LSB	AV_{SS} + 0.5 LSB	AV_{SS} + 2.5 LSB	V	1 LSB = (AVRH – AV_{SS}) / 1024
Full scale transition voltage	V_{FST}	AN0 to AN7	AVRH – 3.5 LSB	AVRH – 1.5 LSB	AVRH + 0.5 LSB	V	
Sampling time	t_{SMP}	—	0.4	—	16500	µs	4.5 V ≤ AVcc ≤ 5.5 V
			1.0				4.0 V ≤ AVcc ≤ 4.5 V
Compare time	t_{CMP}	—	0.66	—	—	µs	4.5 V ≤ AVcc ≤ 5.5 V
			2.2				4.0 V ≤ AVcc ≤ 4.5 V
A/D conversion time	t_{CNV}	—	1.44	—	—	µs	*1
Analog port input current	I_{AIN}	AN0 to AN7	– 0.3	—	+ 10	µA	
Analog input voltage	V_{AIN}	AN0 to AN7	0	—	AVRH	V	
Reference voltage	AV+	AVRH	AVss + 2.7	—	AV_{CC}	V	
Power supply current	I_A	AV_{CC}	—	2.3	6.0	mA	
	I_{AH}		—	—	5	µA	*2
Reference voltage supply current	I_R	AVRH	—	520	900	µA	V_{AVRH} = 5.0 V
	I_{RH}		—	—	5	µA	*2
Inter-channel variation	—	AN0 to AN7	—	—	4	LSB	

*1 : The time per channel (4.5 V ≤ AV_{CC} ≤ 5.5 V, and internal operating frequency = 32 MHz) .

*2 : Defined as supply current (when V_{CC} = AV_{CC} = AVRH = 5.0 V) with A/D converter not operating, and CPU in stop mode.

6. Flash Memory Program/Erase Characteristics

Parameter	Conditions	Value			Unit	Remarks
		Min	Typ	Max		
Sector erase time	T_A = + 25 °C V_{CC} = 5.0 V	—	0.9	3.6	s	Excludes pre-programming before erase
Word (16-bit width) programming time		—	23	370	µs	Excludes system-level overhead
Chip programming time	T_A = + 25 °C, V_{CC} = 5.0 V	—	3.4	55	s	
Erase/program cycle	—	10000	—	—	cycle	
Flash memory data retention time	Average T_A = + 85 °C	20	—	—	year	*

* : This value is calculated from the results of evaluating the reliability of the technology (using Arrhenius equation to translate high temperature measurements into normalized value at + 85 °C) .

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